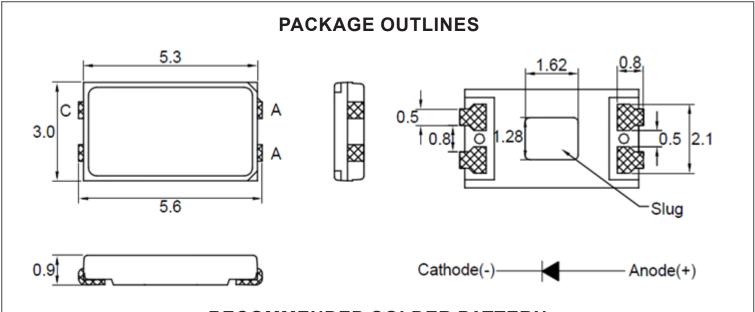
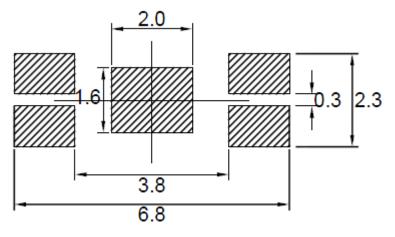


SPECIFICATION CSH563B2C



RECOMMENDED SOLDER PATTERN



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	olor of Emission Lens Type	
CSH563B2C	InGaN	Blue	Water Clear	120°



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ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	150	mA	
Reverse Voltage	VR	5	V	
Operating Temperature Range	Тор	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+100	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	180	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

 $(TA=25^{\circ}C)$

Darameter	Symbol	Toot Condition	Value			Lloit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 150mA	2000	3000	ı	mcd
Forward Voltage	VF	IF = 150mA	-	2.4	3.0	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 150mA	-	120	-	Deg
Dominant Wavelength	λD	IF = 150mA	-	460	-	nm
Spectral Line Half-Width	Δλ	IF = 150mA	-	30	1	nm

^{*}Tolerance of viewing angle: -10 / +5 deg.



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OPTICAL CHARACTERISTIC CURVES

Fig.1 Forward current vs. Forward Voltage

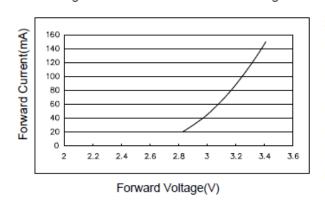


Fig.2 Forward current vs.Luminous Intensity

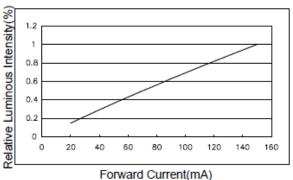
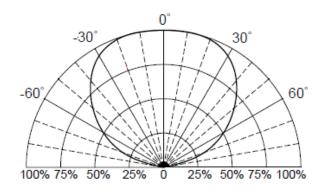
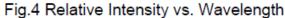
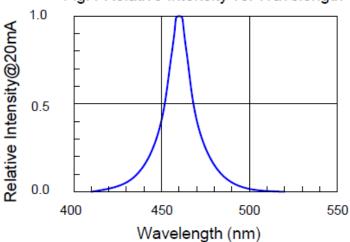


Fig.3 Directivity Radiation







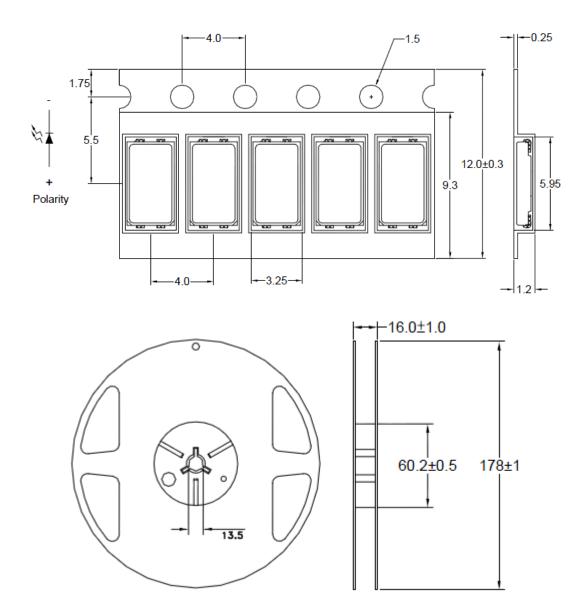


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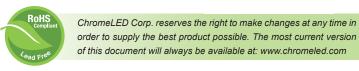
PACKAGING SPECIFICATION

PACKAGING DIMENSION



Notes:

- 1. Tolerance unless mentioned is ± 0.2 mm, Unit=mm.
- 2. 2000pcs/Reel.



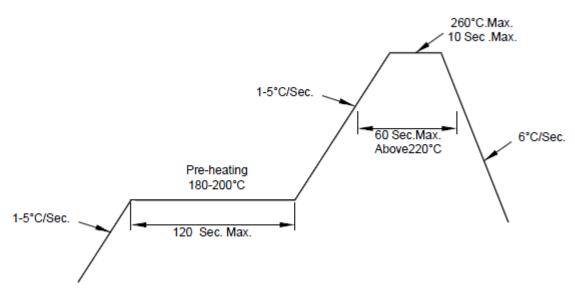


SOLDERING CONDITIONS

RECOMMENDED REFLOW SOLDERING PROFILE

Pb-Free soldering temperature profile

Pb -free solder Temperature profile			
Pre-heat	180-200°C		
Pre-heat time	120 Sec Max		
Peak-Temperature	260°C Max		
Soldering time condition	10 Sec Max		



- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on LEDs during heating.
- After soldering, do not warp the circuit board.
- The encapsulated material of the LEDs is silicone.
- Precautions should be taken to avoid strong pressure on the encapsulated part. So when
 using the chip mounter, the picking up nozzle that does not affect the silicone resin should
 be used.
- Hand soldering should not exceed 3 seconds at maximum 320°C under soldering iron (one time only).

